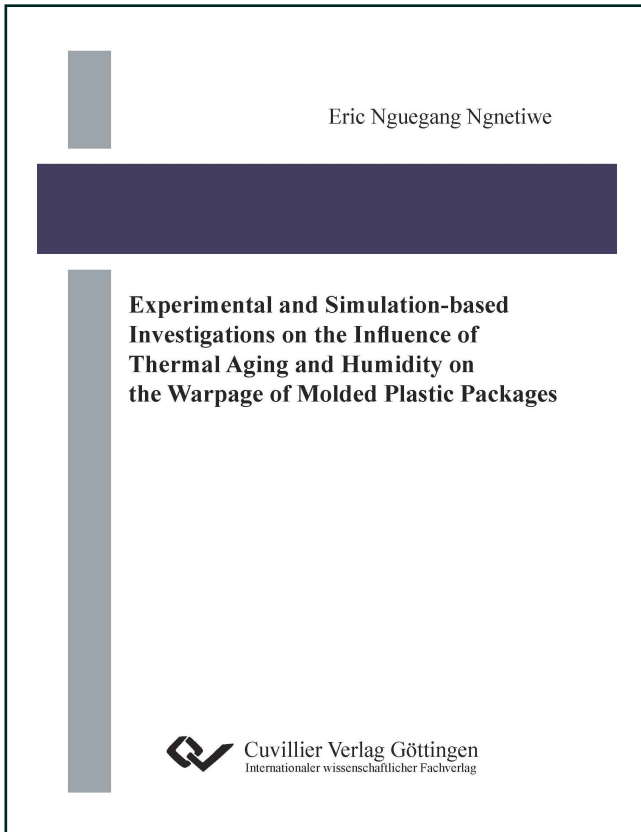




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**Experimental and Simulation-based Investigations
on the Influence of Thermal Aging and Humidity on
the Warpage of Molded Plastic Packages**



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Contents

List of Figures.....	viii
List of Tables.....	xii
List of Symbols.....	xiii
Chapter 0: Zusammenfassung in deutscher Sprache.....	1
0.1. Motivation.....	1
0.2. Zielsetzung der Arbeit.....	2
0.3. Einfluss der thermischen Alterung auf die thermomechanischen Eigenschaften von Klebstoff und Epoxid-Moldmasse.....	4
0.4. Effekte der Materialalterung auf die Verwölbung von mehrkomponentigen Systemen.....	5
0.5. Charakterisierung der Oxidationsschicht.....	6
0.6. Untersuchung der Einflüsse der Feuchte auf die Verwölbung von mehrkomponentigen Systemen.....	10
Chapter 1: Introduction.....	13
1.1. Motivation.....	13
1.2. Objectives Target.....	14
Chapter 2: Basics.....	16
2.1. Materials.....	16
2.1.1. Epoxy Molding Compound (EMC).....	16
2.1.2. Adhesive.....	18
2.1.3. Leadframe.....	18
2.1.4. Physical properties of polymeric material.....	19
2.1.4.1. Coefficient of Thermal Expansion (CTE).....	19
2.1.4.2. Young's Modulus (E).....	20
2.1.4.3. Glass transition temperature (T_g).....	21
2.2. Aging of epoxy molding compound.....	23
2.2.1. Post-mold cure (PMC).....	23
2.2.2. Physical, chemical and thermal aging.....	23
2.3. Moisture in polymeric molding compound.....	24
2.3.1. Mechanism of moisture diffusion.....	24
2.3.2. Diffusion coefficient related to moisture absorption.....	25
2.3.3. Diffusion coefficient related to moisture desorption.....	27
2.3.4. Reversible saturated moisture mass.....	27
2.3.5. Coefficient of Hygroscopic Swelling (CHS).....	28
2.4. Warpage of bi-material systems (Timoshenko's method).....	31
2.5. Testing equipments and methods.....	33
2.5.1. Warpage measurement by using an optical imaging profiler instrument.....	33
2.5.2. Warpage measurement by using a Topography and Deformation Measurement (TDM) Instrument.....	34



2.5.3. Dynamic Mechanical Analysis (DMA).....	35
2.5.4. Thermo-Mechanical Analysis (TMA).....	36
2.5.5. Fluorescence microscopy.....	37
Chapter 3: Effect of thermal aging on the thermo-mechanical properties of adhesive material and epoxy molding compound.....	38
3.1. Introduction.....	38
3.2. Characterization of adhesive material.....	38
3.2.1. Effects of thermal aging on Young's modulus and glass transition Temperature.....	39
3.2.2. Effects of thermal aging on coefficient of thermal expansion and glass transition temperature.....	40
3.3. Characterization of Epoxy Molding Compound.....	41
3.3.1. Epoxy molding compound behavior after post-mold cure.....	42
3.3.2. Epoxy molding compound behavior after reflow soldering.....	44
3.3.3. Epoxy molding compound behavior after temperature storage and temperature Cycling.....	46
3.4. Characterization of Epoxy Molding Compound without oxidation layer.....	49
3.4.1. Bulk Epoxy Molding Compound behaviors after temperature storage.....	50
3.5. Conclusions.....	53
Chapter 4: Effects of material aging on warpage of layered systems.....	54
4.1. Introduction.....	54
4.2. Thermal aging effect of adhesive on warpage of layered systems.....	54
4.2.1. Warpage changes due to temperature cycling.....	55
4.2.2. Warpage changes due to temperature storage.....	56
4.2.3. Comparison and discussion.....	57
4.3. Thermal aging effect of EMC on warpage of layer systems.....	58
4.3.1. Effects of reflow soldering on warpage of layered systems.....	59
4.3.2. Effects of first heating after thermal aging.....	62
4.3.3. Warpage changes of multi-material system due to thermal aging.....	64
4.4. Conclusions.....	66
Chapter 5: Investigation results of oxidation layer.....	68
5.1. Introduction.....	68
5.2. Oxidation layer formation.....	68
5.2.1. Mechanism of formation of oxidation layer.....	69
5.2.2. Thickness versus storage time curve of oxidation layer.....	71
5.2.3. Thickness versus storage temperature.....	73
5.3. Impact of the oxidation layer on EMC warpage.....	74
5.3.1. Impact of storage time on warpage of bi-material systems.....	75
5.3.2. Impact of storage temperature on warpage of bi-material systems.....	76
5.3.3. Impact of oxidation layer thickness on warpage of bi-material systems.....	78
5.3.4. Impact of oxidation layer on the shift of the zero-warpage temperature.....	79
5.4. Characterization of oxidation layer.....	83
5.4.1. Characterization of coefficient of thermal expansion and glass transition temperature of oxidation layer.....	83
5.4.2. Characterization of Young's modulus of oxidation layer.....	87



5.4.3. Verification.....	92
5.5. Epoxy Molding Compound shrinkage due to thermal aging.....	95
5.5.1. Mass change due to thermal aging.....	96
5.5.2. Density change due to thermal aging.....	98
5.5.3. Volume change due to thermal aging.....	98
5.6. Conclusions.....	99
Chapter 6: Investigation results of moisture effect.....	102
6.1. Introduction.....	102
6.2. Moisture absorption in epoxy molding compound.....	104
6.2.1. Mass gain curve.....	104
6.2.2. Impact of sample geometries on absorption behaviour of EMC.....	106
6.2.3. Impact of absorbed moisture at room air condition on absorption capacity of EMC.....	107
6.2.4. Validation of calculated diffusion coefficient.....	109
6.3. Moisture desorption.....	110
6.3.1. Relative mass loss versus exposure time curve.....	110
6.3.2. Desorption coefficient.....	111
6.3.3. Desorption parameters.....	112
6.3.4. Validation of calculated desorption parameter.....	113
6.4. Characterization of coefficient of hygroscopic swelling (CHS).....	113
6.4.1. Method1: characterization of CHS by means of TDM equipment.....	114
6.4.2. Method2: characterization of CHS by using TMA/TGA technique.....	116
6.5. Impacts of moisture on warpage of bi-material samples during reflow soldering.....	119
6.5.1. Warpage changes due to moisture absorption.....	120
6.5.2. FEA based verification of both simulation method.....	121
6.5.3. Impact of reflow soldering on warpage of saturated bi-material samples....	122
6.6. Conclusions.....	123
Chapter 7: Conclusions and outlook.....	125
7.1. Conclusions.....	125
7.2. Outlook.....	128
References.....	129